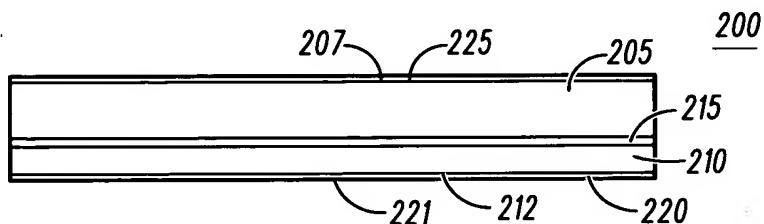


**FIG. 1**

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FORM A METAL SUPPORT LAYER AND A CONDUCTIVE METAL FOIL LAYER JOINED BY AN INORGANIC RELEASE MATERIAL

COAT A SURFACE OF THE CONDUCTIVE METAL FOIL LAYER WITH A HIGH TEMPERATURE ANTI-OXIDANT MATERIAL



**FIG. 2**

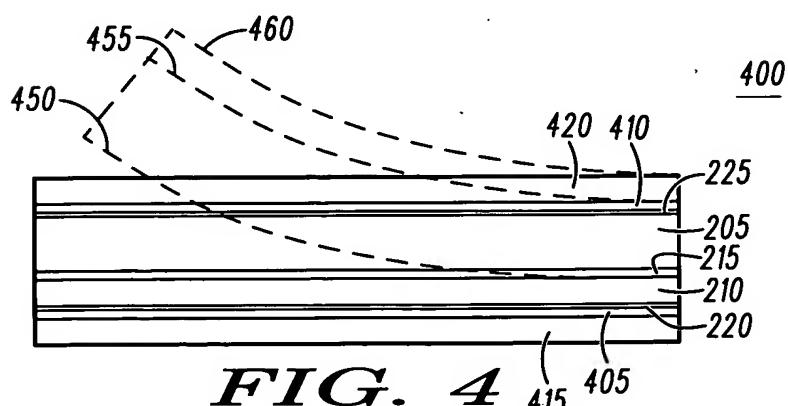
FORM A CRYSTALLIZED DIELECTRIC OXIDE LAYER ON THE CONDUCTIVE METAL FOIL

FORM AN ELECTRODE LAYER ADJACENT THE CRYSTALLIZED DIELECTRIC OXIDE LAYER ON THE CONDUCTIVE METAL FOIL

LAMINATE PEELABLE CIRCUIT BOARD FOIL TO A LAYER OF A CIRCUIT BOARD

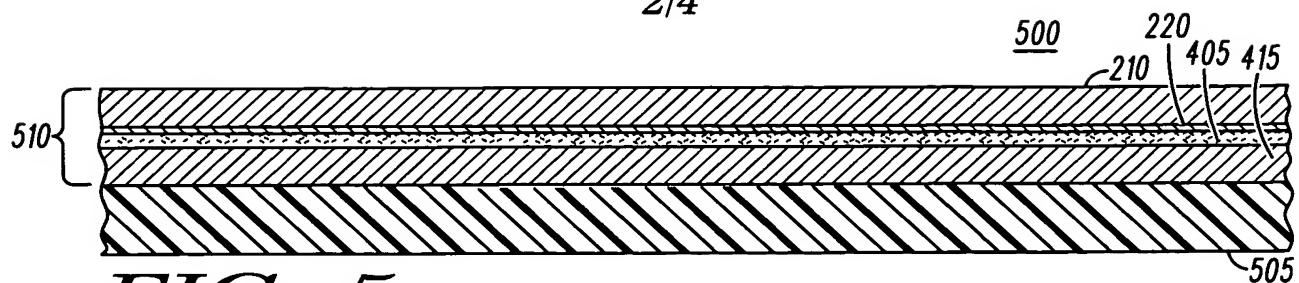
PEEL AWAY THE METAL SUPPORT LAYER AND OTHER SACRIFICIAL LAYERS

**FIG. 3**

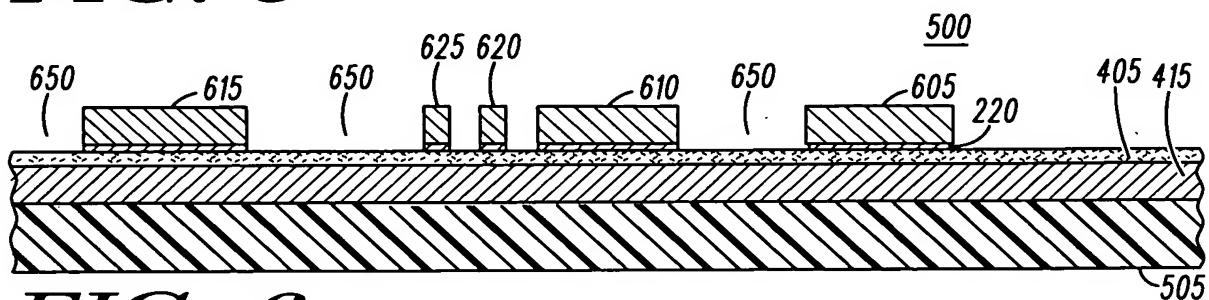


**FIG. 4**

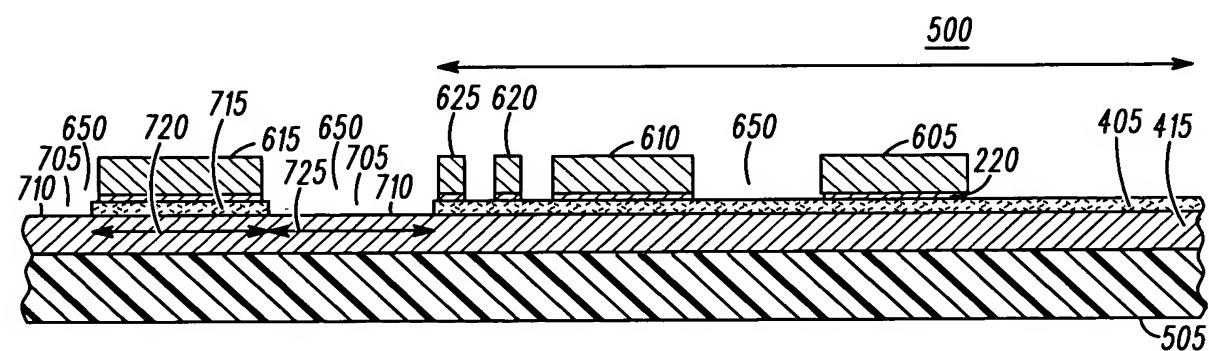
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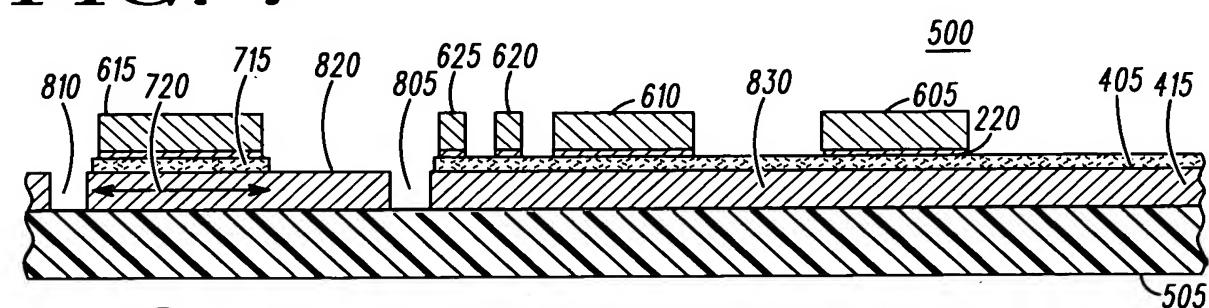
**FIG. 5**



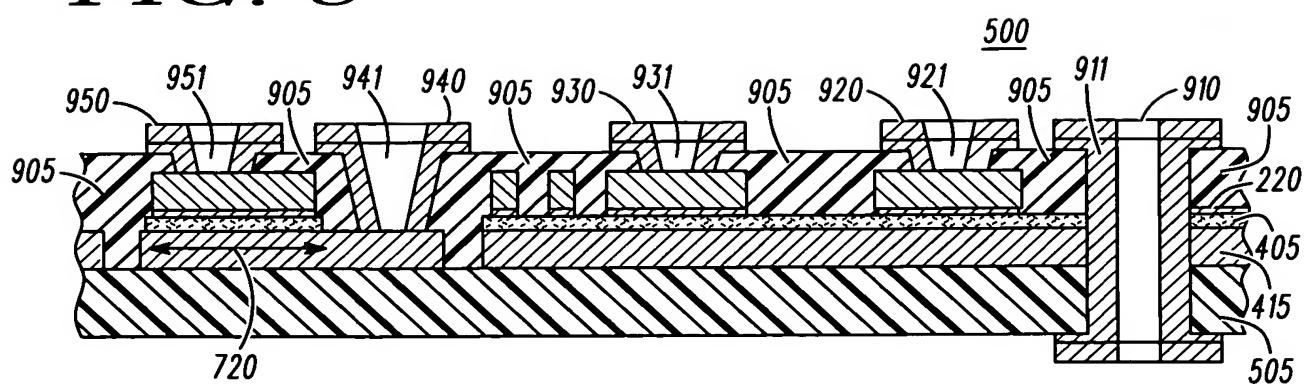
**FIG. 6**



**FIG. 7**

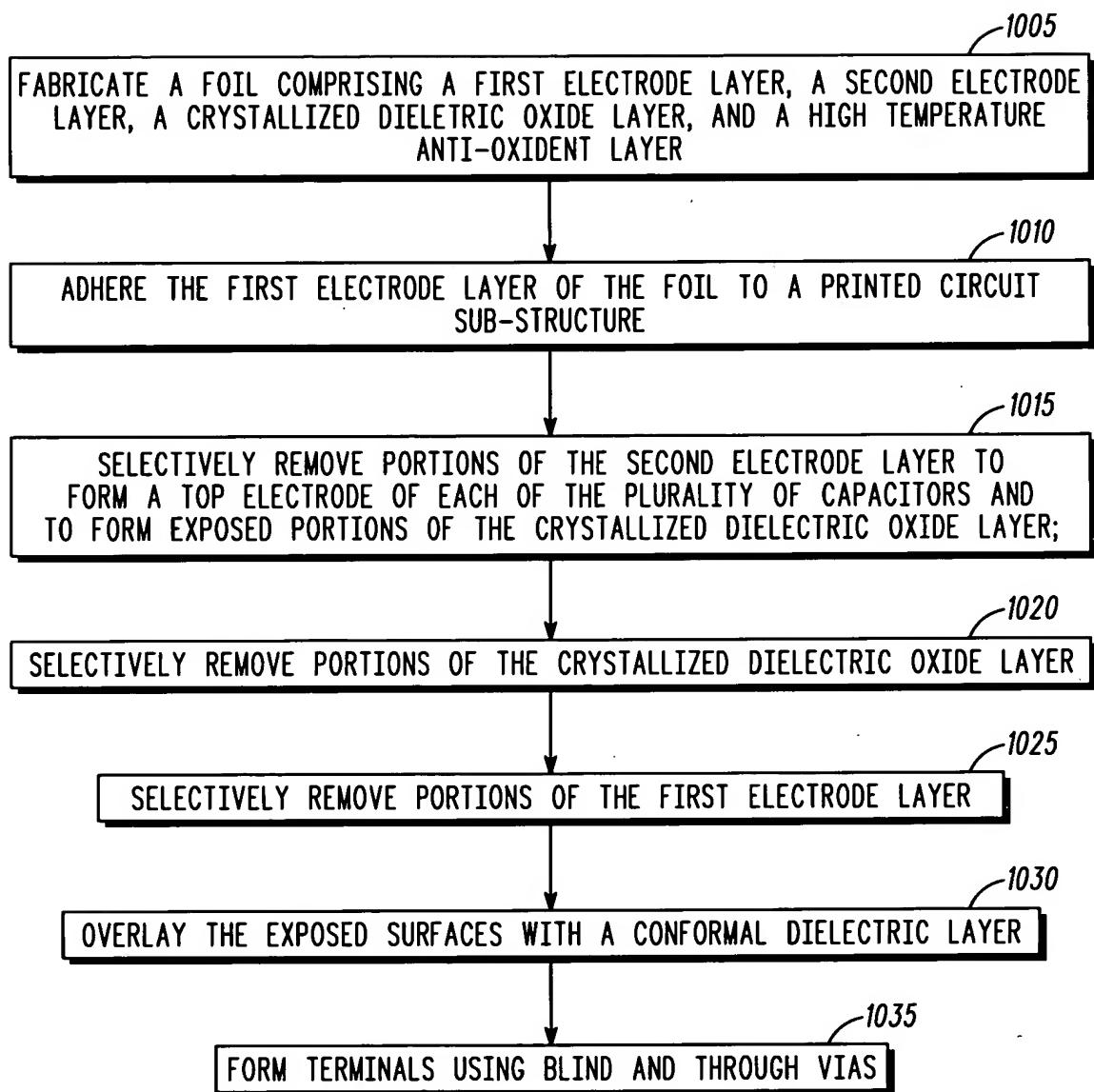


**FIG. 8**



**FIG. 9**

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**FIG. 10**

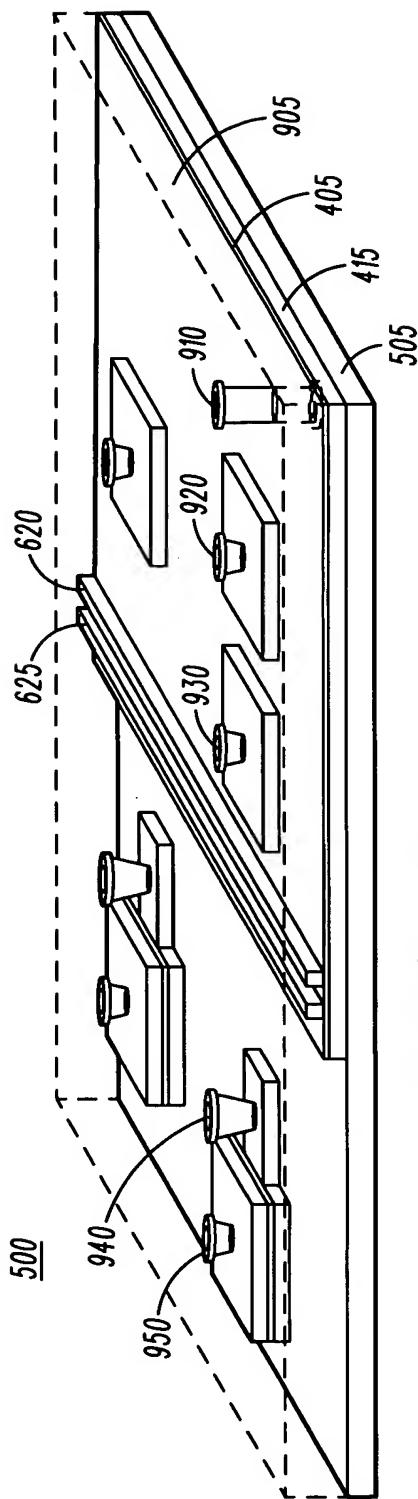


FIG. 11

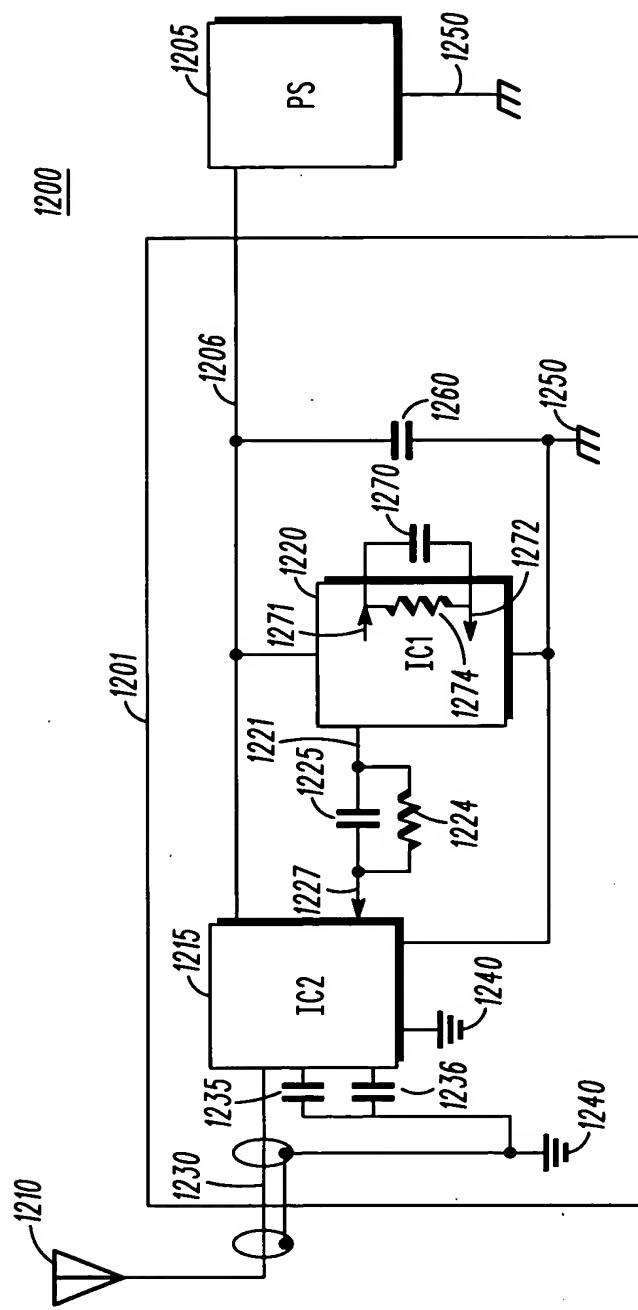


FIG. 12